

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

DECLARATION FOR PATENT APPLICATION

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled:

STACKED DIE CONNECTION USING STAND OFF STITCH
BONDING

the specification of which is attached hereto.

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by an amendment, if any, specifically referred to in this oath or declaration.

I acknowledge the duty to disclose all information known to me which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code § 119/365 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)			Priority Not Claimed
_____ (Number)	_____ (Country)	_____ (Filing Date)	<input type="checkbox"/>
_____ (Number)	_____ (Country)	_____ (Filing Date)	<input type="checkbox"/>
_____ (Number)	_____ (Country)	_____ (Filing Date)	<input type="checkbox"/>

I hereby claim the benefit under Title 35, United States Code, § 120/365 of any United States and PCT international application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code,

§ 112, I acknowledge the duty to disclose all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56(a) which became available between the filing date of the prior application and the national or PCT international filing date of this application:

(Application No.)	(Filing Date)	(Status) (patented, pending, abandoned)
(Application No.)	(Filing Date)	(Status) (patented, pending, abandoned)
(Application No.)	(Filing Date)	(Status) (patented, pending, abandoned)

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Please address all correspondence to Thomas J. D'Amico of **Dickstein Shapiro Morin & Oshinsky LLP** located at 2101 L Street NW, Washington, DC 20037-1526. Telephone calls should be made to (202) 785-9700.

Full name of sole inventor: Neal M. Bowen

Inventor's signature: Neal M. Bowen Date: 11-26-01

Residence:

Citizenship:

Mailing Address:

10002475.126501

Micron Docket No.: 01-0586
Docket No.: M4065.0493/P493
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Neal M. Bowen

Application No.: Not Yet Assigned

Group Art Unit: N/A

Filed: Concurrently Herewith

Examiner: Not Yet Assigned

For: STACKED DIE CONNECTION USING
STAND OFF STITCH BONDING

**POWER OF ATTORNEY BY ASSIGNEE AND
CERTIFICATE BY ASSIGNEE UNDER 37 CFR § 3.73(B)**

Assistant Commissioner for Patents
Washington, DC 20231

Dear Sir:

Micron Technology, Inc., Assignee of the entire right, title and interest in the above-identified application by virtue of the Assignment attached hereto (which is also being submitted concurrently for recordation), hereby appoints the attorneys and agents of the firm of Dickstein Shapiro Morin & Oshinsky LLP located at 2101 L Street NW, Washington, DC 20037-1526, listed as follows:

Gary M. Hoffman	26,411	Laurence E. Fisher	37,131	Gianni Minutoli	41,198
Thomas J. D'Amico	28,371	John C. Luce	34,378	Michael Bergman	42,318
Donald A. Gregory	28,954	William E. Powell, III	39,803	Mark E. Strickland	45,138
James W. Brady, Jr.	32,115	Patrick T. Skacel	47,948	Salvatore P. Tamburo	45,153
Jon D. Grossman	32,699	Gary L. Veron	39,057	Peter Veytsman	45,920
Mark J. Thronson	33,082	Mialeeka C. Williams-Bibbs	48,037	Christopher S. Chow	46,493
Eric Oliver	35,307	Jeremy A. Cubert	40,399		

and also, listed as follows:

Michael Lynch	30,871	David Paul	34,692	Charles Brantley	38,086
Kevin Martin	37,882	Walter Fields	37,130		

Application No.: Not Yet Assigned

Micron Docket No.: 01-0586
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attorneys of Micron Technology, Inc. as its attorneys with full power of substitution to prosecute this application and to transact all business in the Patent and Trademark Office in connection therewith.


The Assignee certifies that the above-identified assignment has been reviewed and to the best of the Assignee's knowledge and belief, title is in the assignee.

Please direct all correspondence regarding this application to the following:

Thomas J. D'Amico
DICKSTEIN SHAPIRO MORIN & OSHINSKY LLP
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Respectfully submitted,

MICRON TECHNOLOGY, INC.



Michael L. Lynch
Chief Patent Counsel
Registration No. 30,871

Dated: 11-29-01

10002175-120501